

»Features

- 25Watts peak pulse power (tp = 8/20µs)
- Unidirectional configurations
- Solid-state silicon-avalanche technology
- Low clamping voltage
- Low leakage current
- Low capacitance (Cj=0.3pF typ. I/O to I/O)
- IEC 61000-4-2 ±10kV contact ±12kV air
- Low clamping voltage: VCL = 5.3V typ @ IPP =16A (TLP)
- IEC 61000-4-5 (Lightning) 5A (8/20µs)



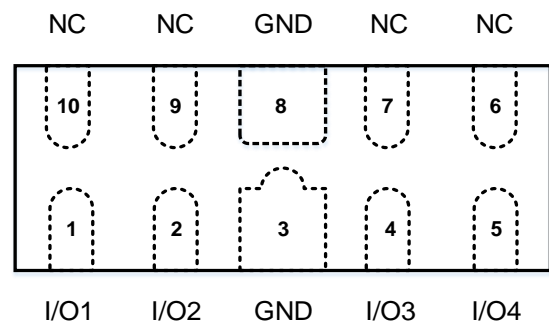
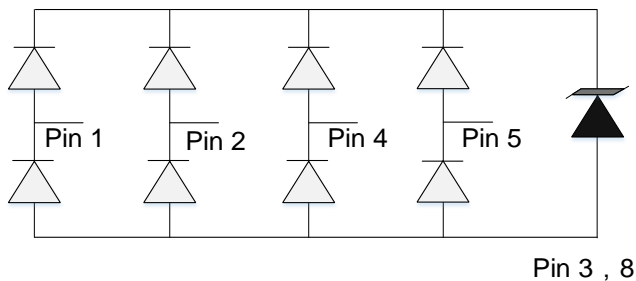
»Applications

- USB 3.0 and USB3.1
- HDMI1.3,HDMI1.4 and HDMI2.0
- Very sensitive interface lines
- Notebooks, Desktops, and Servers
- Industrial equipment

»Mechanical Data

- Tiny DFN10L(2.5mmx1.0mm) package
- Molding compound flammability rating: UL 94V-0
- Packaging: Tape and Reel
- RoHS/WEEE Compliant

»Schematic & PIN Configuration



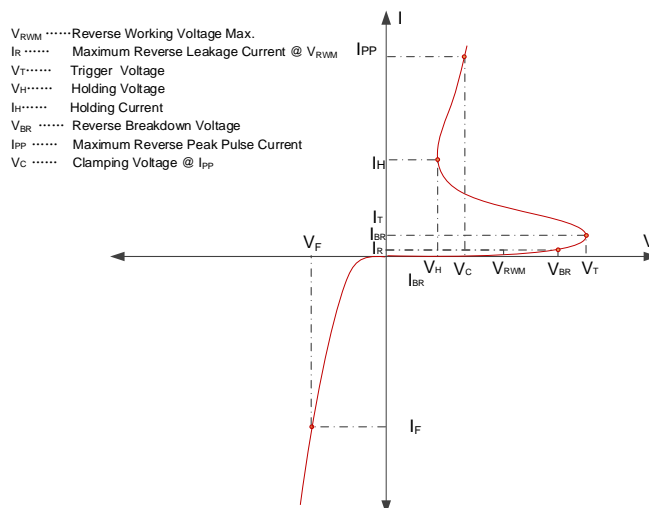
»Absolute Maximum Rating

Rating	Symbol	Value	Units
Peak Pulse Power ( $t_p=8/20\mu s$ )	$P_{PP}$	25	Watts
Peak Pulse Current ( $t_p=8/20\mu s$ ) (note1)	$I_{PP}$	5	A
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	$V_{ESD}$	12 10	kV
Lead Soldering Temperature	$T_L$	260(10seconds)	°C
Junction Temperature	$T_J$	-55 to + 125	°C
Storage Temperature	$T_{stg}$	-55 to + 125	°C

»Electrical Characteristics

Parameter	Symbol	Conditions	Min	Typical	Max	Units
Reverse Stand-Off Voltage	$V_{RWM}$				3.3	V
Holding Voltage	$V_H$		2.0		3.3	V
Reverse Leakage Current	$I_R$	$V_{RWM}=3.3V, T=25^\circ C$			500	nA
Trigger Voltage	$V_T$			8.0		
Clamping Voltage	$V_{CL}$	$I_{PP}=16A, t_p=100ns$		5.3	6	V
Clamping Voltage	$V_C$	$I_{PP}=5A, t_p=8/20\mu s$			5	V
dynamic resistance	$R_{dyn}$	$T_{amb}=25^\circ C, I_R=10A$		0.3	0.4	$\Omega$
Junction Capacitance	$C_j$	$V_R = 0V, f = 1MHz$ I/O to I/O		0.3		pF
		$V_R = 0V, f = 1MHz$ I/O to GND		0.55		pF

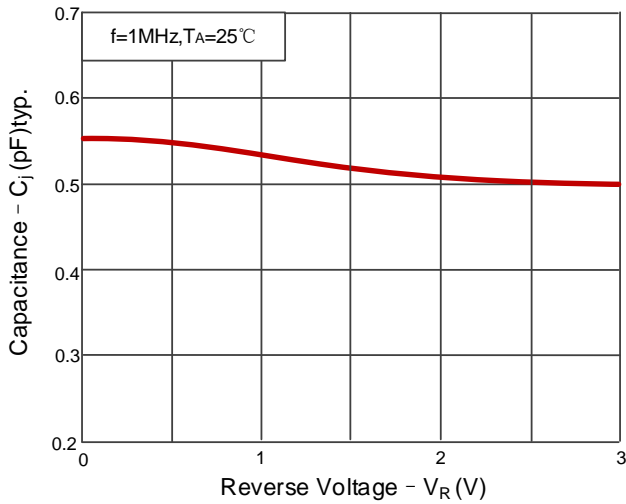
»Electrical Parameters (I/O to GND,  $T_A = 25^\circ C$  unless otherwise noted)



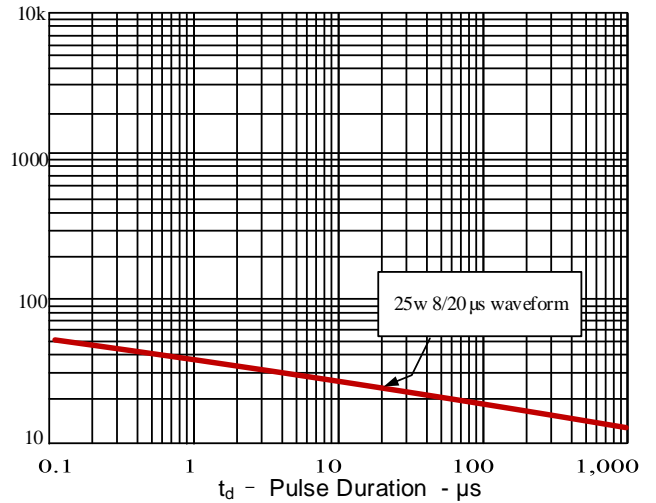
Note: 8/20 $\mu s$  pulse waveform.

»Typical Characteristic Curves

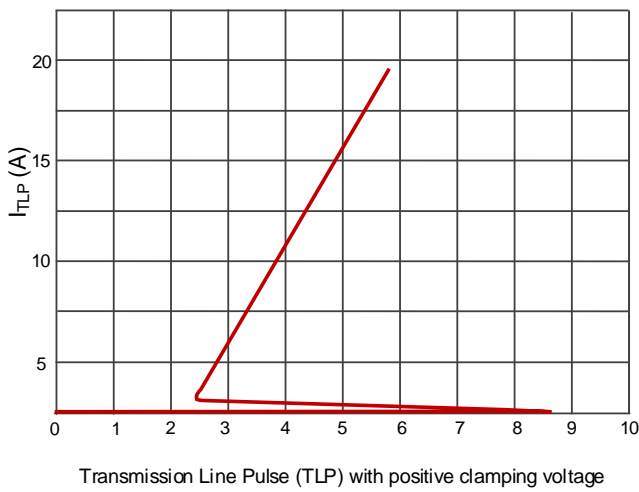
Capacitance vs. Reverse Voltage



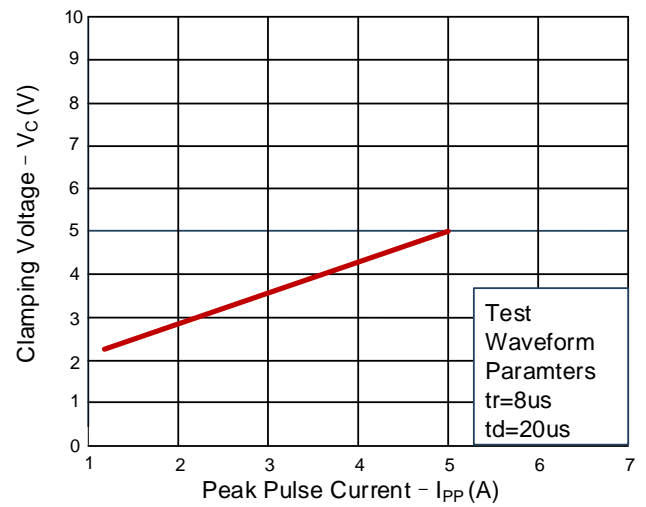
Peak Pluse Power vs. Pluse Time



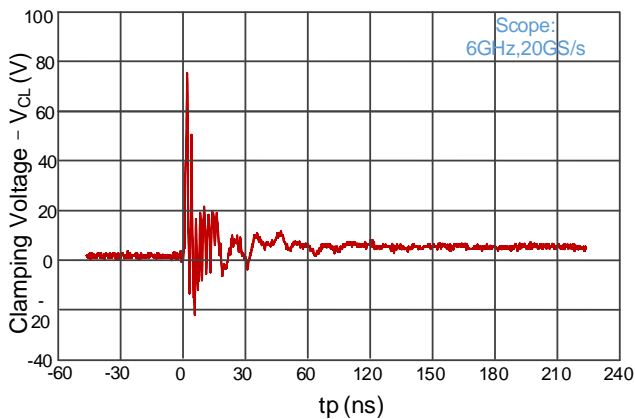
Positive Clamping voltage (TLP)



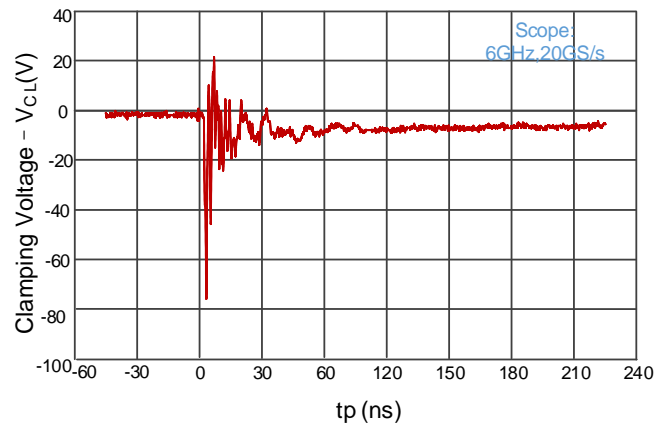
Reverse Clamping Voltage vs. Peak Pulse Current



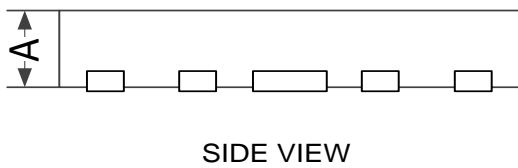
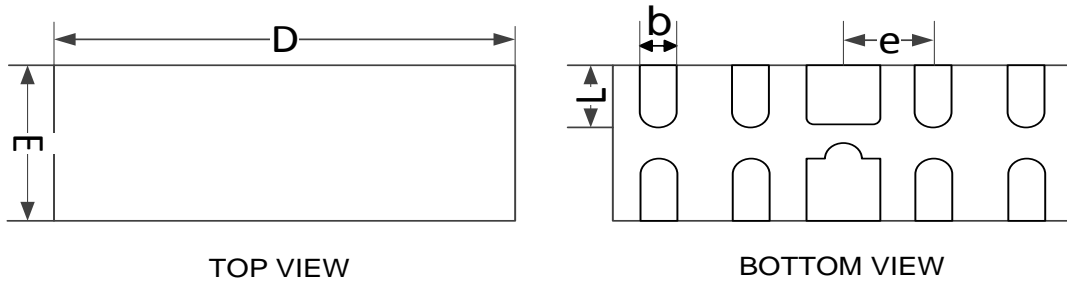
IEC61000-4-2 : 8 kV positive pulse(I/O to GND)



IEC61000-4-2 : 8 kV positive pulse(GND to I/O)

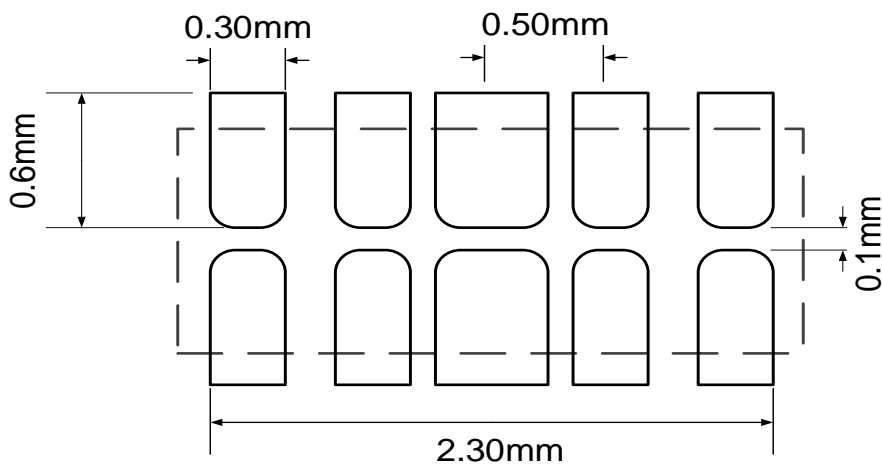


»Package information – DFN10L(2.5mmx1.0mm)



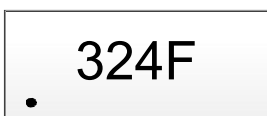
COMMON DIMENSION (mm)			
PKG	DFN2510-10L		
REF.	MIN.	NOM.	MAX.
A	0.450	0.500	0.600
b	0.150	0.200	0.250
D	2.450	2.500	2.550
E	0.950	1.000	1.050
e	0.500BSC		
L	0.350	0.400	0.450

»Recommend PCB Layout



Notes: This PCB Layout Is For Reference Purposes Only.

»Marking



»Ordering information

Order code	Package	Base qty	Delivery mode
RCLAMP3324P-N	DFN10L(2.5mmx1.0mm)	3k	Tape and reel